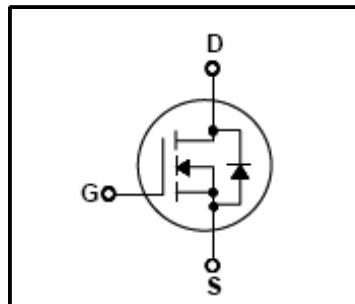


**Silicon N-Channel MOSFET**

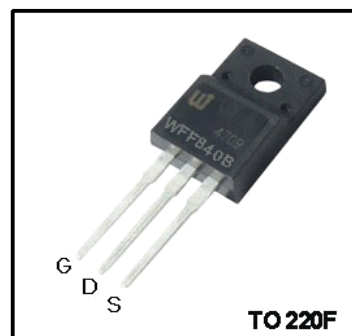
**Features**

- 9A,500V,  $R_{DS(on)}$ (Max0.75 $\Omega$ )@ $V_{GS}=10V$
- Ultra-low Gate charge(Typical 28nC)
- Fast Switching Capability
- 100%Avalanche Tested
- Maximum Junction Temperature Range(150 $^{\circ}C$ )



**General Description**

This Power MOSFET is produced using Winsemi's advanced planar stripe, DMOS technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. This devices is specially well suited for high efficiency switch model power supplies, power factor correction and half bridge and full bridge resonant topology line a electronic lamp ballast.



**Absolute Maximum Ratings**

| Symbol         | Parameter                                       | Value    | Units          |
|----------------|---|----------|----------------|
| $V_{DSS}$      | Drain Source Voltage                            | 500      | V              |
| $I_D$          | Continuous Drain Current(@ $T_c=25^{\circ}C$ )  | 9*       | A              |
|                | Continuous Drain Current(@ $T_c=100^{\circ}C$ ) | 5.4*     | A              |
| $I_{DM}$       | Drain Current Pulsed (Note1)                    | 36*      | A              |
| $V_{GS}$       | Gate to Source Voltage                          | $\pm 30$ | V              |
| $E_{AS}$       | Single Pulsed Avalanche Energy (Note2)          | 360      | mJ             |
| $E_{AR}$       | Repetitive Avalanche Energy (Note1)             | 13.5     | mJ             |
| dv/dt          | Peak Diode Recovery dv /dt (Note3)              | 4.5      | V/ ns          |
| $P_D$          | Total Power Dissipation(@ $T_c=25^{\circ}C$ )   | 135      | W              |
|                | Derating Factor above 25 $^{\circ}C$            | 1.07     | W/ $^{\circ}C$ |
| $T_J, T_{stg}$ | Junction and Storage Temperature                | -55~150  | $^{\circ}C$    |
| $T_L$          | Channel Temperature                             | 300      | $^{\circ}C$    |

\*Drain current limited by maximum junction temperature

**Thermal Characteristics**

| Symbol    | Parameter                                 | Value |     |      | Units         |
|-----------|---|-------|-----|------|---------------|
|           |   | Min   | Typ | Max  |               |
| $R_{QJC}$ | Thermal Resistance , Junction -to -Case   | -     | -   | 0.93 | $^{\circ}C/W$ |
| $R_{QCS}$ | Thermal Resistance , Case-to-Sink         | -     | 0.5 | -    | $^{\circ}C/W$ |
| $R_{QJA}$ | Thermal Resistance , Junction-to -Ambient | -     | -   | 62.5 | $^{\circ}C/W$ |

**Electrical Characteristics(Tc=25 °C)**

| Characteristics                                | Symbol                         | Test Condition   | Min  | Type | Max  | Unit |    |
|--|--------------------------------|--|--|------|------|------|----|
| Gate leakage current                           | I <sub>GSS</sub>               | V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V                | -  | -    | ±100 | nA   |    |
| Gate-source breakdown voltage                  | V <sub>(BR)GSS</sub>           | I <sub>G</sub> =±10 μA,V <sub>DS</sub> =0V               | ±30  | -    | -    | V    |    |
| Drain cut -off current                         | I <sub>DSS</sub>               | V <sub>DS</sub> =500V,V <sub>GS</sub> =0V                | -  | -    | 1    | μA   |    |
|  |                                | V <sub>DS</sub> =400V,TC=125 °C                          |  |      | 10   | μA   |    |
| Drain -source breakdown voltage                | V <sub>(BR)DSS</sub>           | I <sub>D</sub> =250 μA,V <sub>GS</sub> =0V               | 500  | -    | -    | V    |    |
| Breakdown voltage Temperature Coefficient      | $\Delta BV_{DSS} / \Delta T_J$ | I <sub>D</sub> =250μA,Referenced to 25 °C                | -  | 0.57 | -    | V/°C |    |
| Gate threshold voltage                         | V <sub>GS(th)</sub>            | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250 μA | 3  | -    | 5    | V    |    |
| Drain -source ON resistance                    | R <sub>DS(ON)</sub>            | V <sub>GS</sub> =10V,I <sub>D</sub> =4.5A                | -  | -    | 0.75 | Ω    |    |
| Forward Transconductance                       | g <sub>fs</sub>                | V <sub>DS</sub> =40V,I <sub>D</sub> =4.5A                | -  | 6.5  | -    | S    |    |
| Input capacitance                              | C <sub>iss</sub>               | V <sub>DS</sub> =25V,                                    | -  | 790  | 1030 | pF   |    |
| Reverse transfer capacitance                   | C <sub>rss</sub>               | V <sub>GS</sub> =0V,                                     | -  | 24   | 30   |      |    |
| Output capacitance                             | C <sub>oss</sub>               | f=1MHz   | -  | 130  | 170  |      |    |
| Switching time                                 | Rise time                      | tr   | V <sub>DD</sub> =250V,<br>I <sub>D</sub> =9A<br>R <sub>G</sub> =25Ω<br><br>(Note4,5) | -    | 65   | 140  | ns |
|  | Turn-on time                   | ton  |  | -    | 18   | 15   |    |
|  | Fall time                      | tf   |  | -    | 64   | 125  |    |
|  | Turn-off time                  | toff   |  | -    | 93   | 195  |    |
| Total gate charge(gate-source plus gate-drain) | Q <sub>g</sub>                 | V <sub>DD</sub> =400V,<br>V <sub>GS</sub> =10V,          | -  | 28   | 35   | nC   |    |
| Gate-source charge                             | Q <sub>gs</sub>                | I <sub>D</sub> =9A                                       | -  | 4    | -    |      |    |
| Gate-drain("miller") Charge                    | Q <sub>gd</sub>                | (Note4,5)  | -  | 15   | -    |      |    |

**Source-Drain Ratings and Characteristics(Ta=25 °C)**

| Characteristics                  | Symbol           | Test Condition                           | Min | Type | Max | Unit |
|----------------------------------|------------------|--|-----|------|-----|------|
| Continuous drain reverse current | I <sub>DR</sub>  | -  | -   | -    | 9   | A    |
| Pulse drain reverse current      | I <sub>DRP</sub> | -  | -   | -    | 36  | A    |
| Forward voltage(diode)           | V <sub>DSF</sub> | I <sub>DR</sub> =9A,V <sub>GS</sub> =0V  | -   | -    | 1.4 | V    |
| Reverse recovery time            | trr              | I <sub>DR</sub> =9A,V <sub>GS</sub> =0V, | -   | 335  | -   | ns   |
| Reverse recovery charge          | Q <sub>rr</sub>  | dI <sub>DR</sub> / dt =100 A / μs        | -   | 2.95 | -   | μC   |

Note 1.Repeativity rating :pulse width limited by junction temperature

2.L=8mH I<sub>AS</sub>=9A,V<sub>DD</sub>=50V,R<sub>G</sub>=25Ω,Starting T<sub>J</sub>=25 °C

3.I<sub>SD</sub>≤9A,di/dt≤200A/us,V<sub>DD</sub><BV<sub>DSS</sub>,STARTING T<sub>J</sub>=25 °C

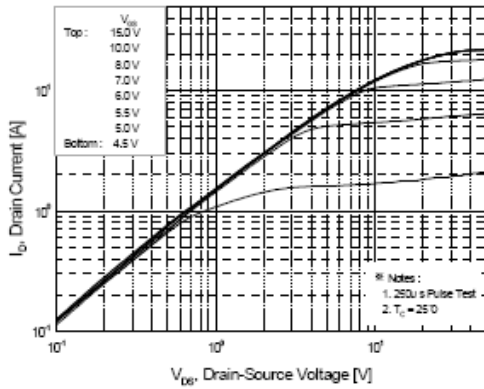
4.Pulse Test:Pulse Width≤300us,Duty Cycle≤2%

5. Essentially independent of operating temperature.

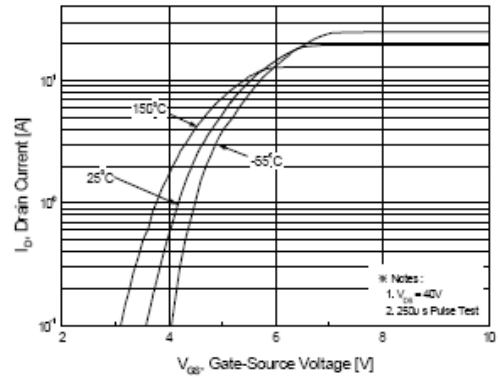
This transistor is an electrostatic sensitive device

Please handle with caution

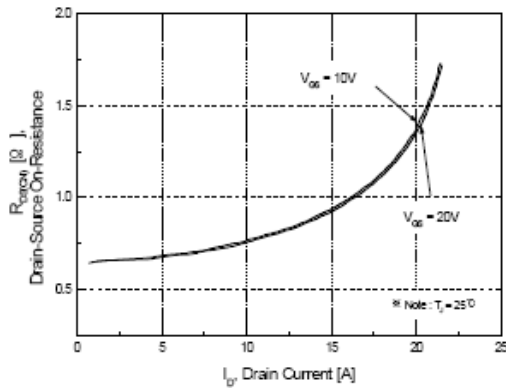




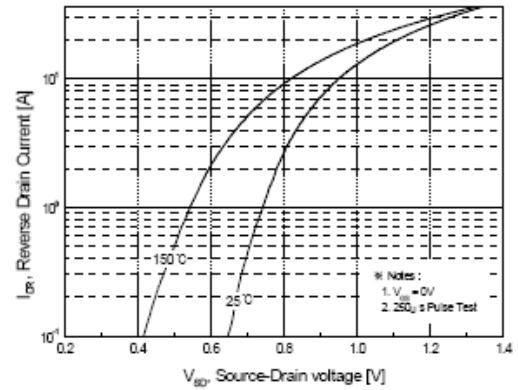
**Fig.1 On State Characteristics**



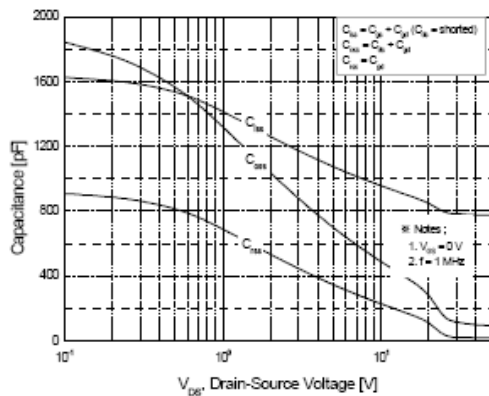
**Fig.2 Transfer Characteristics**



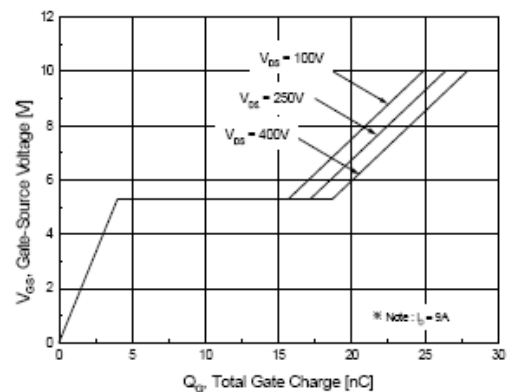
**Fig.3 On-Resistance Variation vs Drain Current And Gate Voltage**



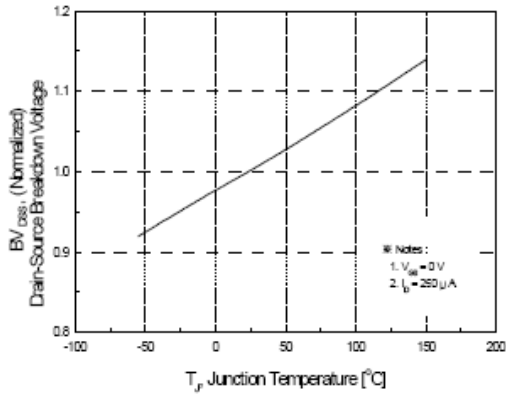
**Fig.4 Body Diode Forward Voltage Variation with Source Current and Temperature**



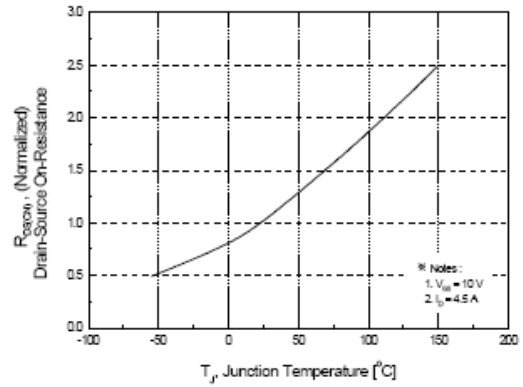
**Fig.5 Capacitance Characteristics**



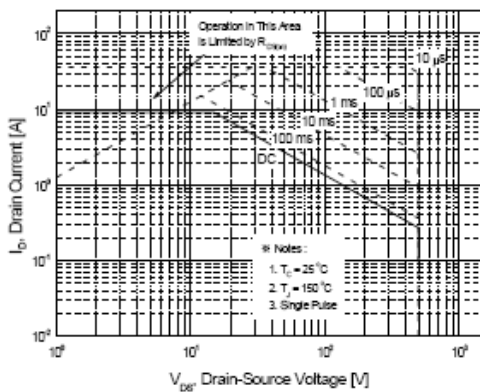
**Fig.6 Gate Charge Characteristics**



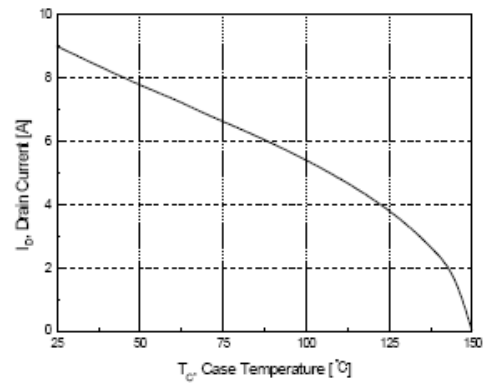
**Fig.7 Breakdown Voltage Variation Vs Temperature**



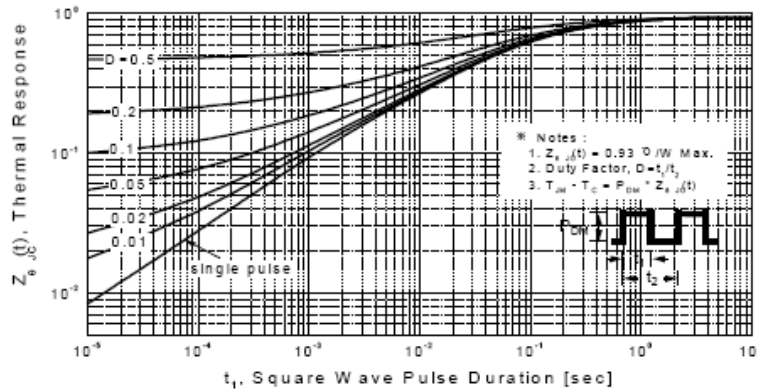
**Fig.8 On-Resistance Variation vs. Temperature**



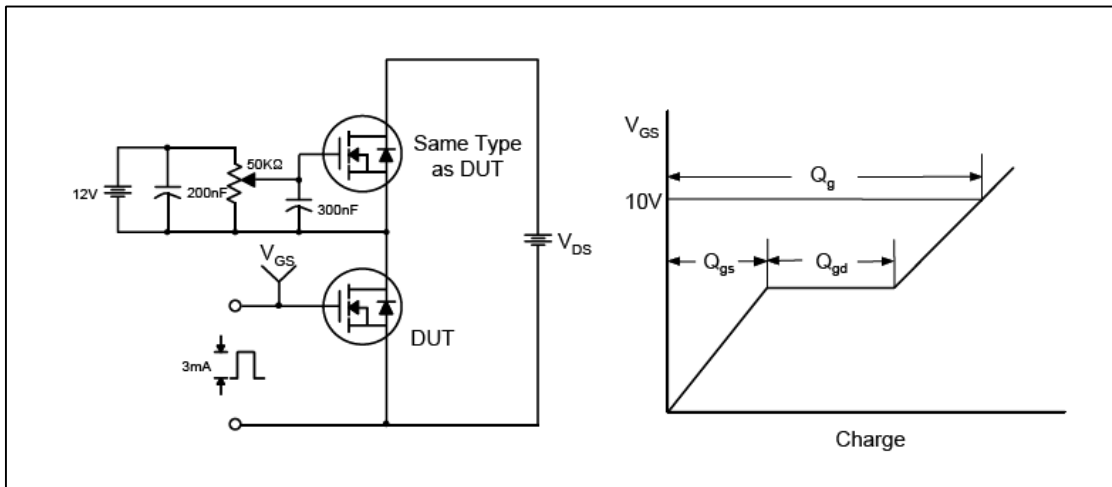
**Fig.9 Maximum Safe Operation Area**



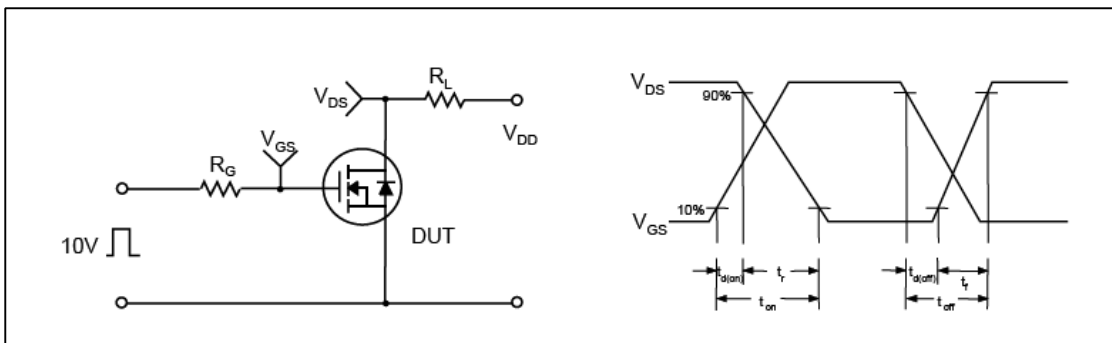
**Fig.10 Maximum Drain Current vs Case temperature**



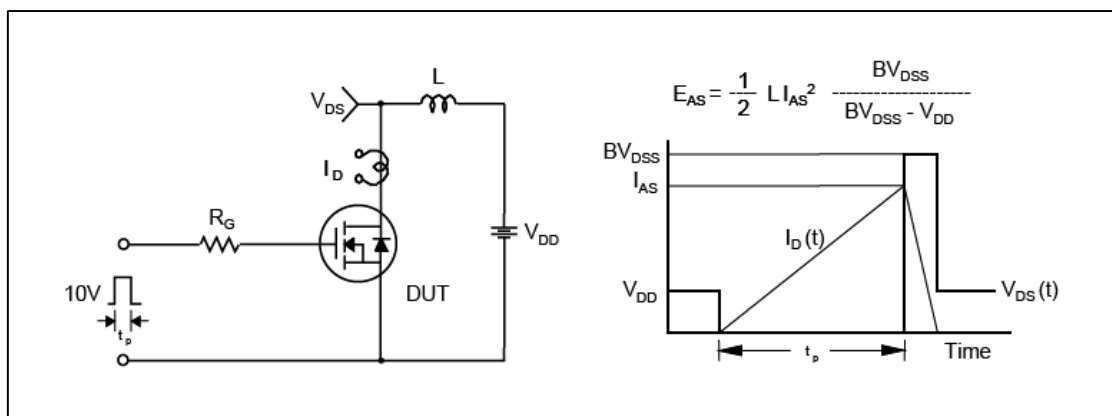
**Fig.11 Transient thermal Response Curve**



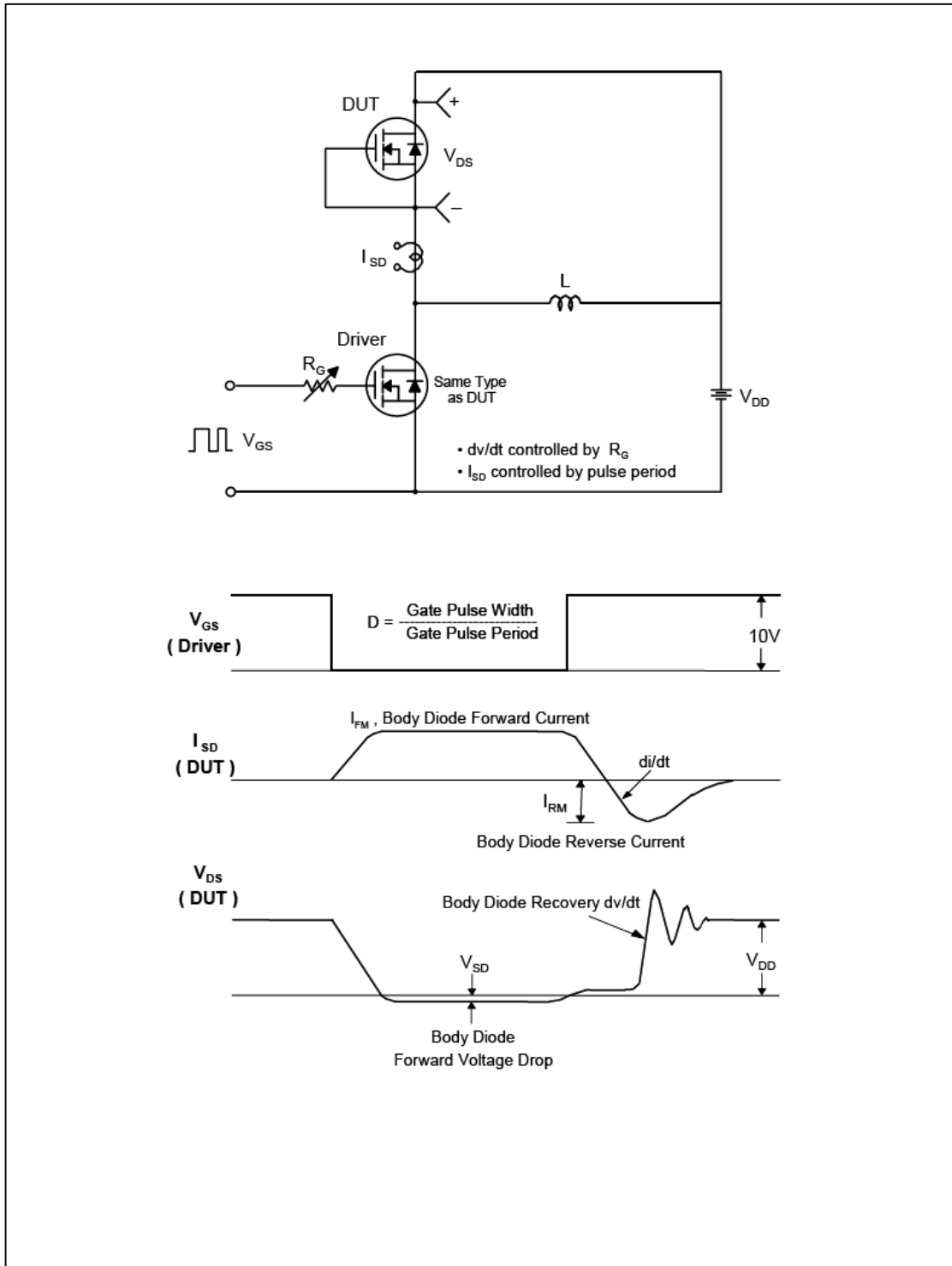
**Fig.12 Gate Test circuit & Waveform**



**Fig.13 Resistive Switching Test Circuit & Waveform**



**Fig.14 Unclamped Inductive Switching Test Circuit & Waveform**



**Fig.15 Peak Diode Recovery  $dv/dt$  Test Circuit & Waveform**

**TO-220F Package Dimension**

